

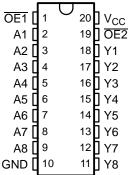


FEATURES

- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication
- Extended Temperature Performance of -40°C to 125°C
- **Enhanced Diminishing Manufacturing** Sources (DMS) Support
- **Enhanced Product-Change Notification**
- Qualification Pedigree (1)
- Operates From 2 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 5.3 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot) >2 V at $V_{CC} = 3.3 \text{ V}, T_{\Delta} = 25^{\circ}\text{C}$
- Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V
- Ioff Supports Partial-Power-Down Mode Operation

DW OR PW PACKAGE (TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

The SN74LVC540A-EP octal buffer/driver is designed for 2.7-V to 3.6-V V_{CC} operation.

This device is ideal for driving bus lines or buffer-memory address registers. This device features inputs and outputs on opposite sides of the package that facilitate printed circuit board layout.

The 3-state control gate is a 2-input AND gate with active-low inputs so that, if either output-enable (OE1) or OE2) input is high, all outputs are in the high-impedance state.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

T _A	PACKA	GE ⁽¹⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC - DW	Reel of 2000	SN74LVC540AQDWREP	C540AEP
	TSSOP – PW	Reel of 2000	SN74LVC540AQPWREP	C540AEP

Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



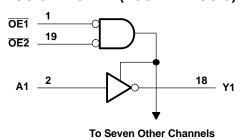
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FUNCTION TABLE

	INPUTS	OUTPUT	
OE1	OE2	Α	Y
L	L	L	Н
L	L	Н	L
Н	X	X	Z
X	Н	X	Z

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		-0.5	6.5	V
VI	Input voltage range ⁽²⁾	-0.5	6.5	V	
Vo	Voltage range applied to any output in the high-imp	-0.5	6.5	V	
Vo	Voltage range applied to any output in the high or I	-0.5	V _{CC} + 0.5	V	
I _{IK}	Input clamp current	V _I < 0		-50	mA
lok	Output clamp current	V _O < 0		-50	mA
I _O	Continuous output current			±50	mA
	Continuous current through V _{CC} or GND			±100	mA
0	Decline the supplication of the supplication (4)	DW package		58	0000
θ_{JA}	Package thermal impedance ⁽⁴⁾	PW package		83	°C/W
T _{stg}	Storage temperature range ⁽⁵⁾		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

⁽²⁾ The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

⁽³⁾ The value of V_{CC} is provided in the recommended operating conditions table.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51-7.

⁽⁵⁾ Long-term high-temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See http://www.ti.com/ep_quality for additional information on enhanced plastic packaging.



Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
V	Cumply voltage	Operating	2	3.6	V
V _{CC}	Supply voltage	Data retention only	1.5		V
V_{IH}	High-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		V
V_{IL}	Low-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	V
V_{I}	Input voltage		0	5.5	V
\/	Output voltage	High or low state	0	V_{CC}	V
Vo	Output voltage	3-state	0	5.5	
	High-level output current	$V_{CC} = 2.7 \text{ V}$		-12	A
ЮН	nigir-level output current	$V_{CC} = 3 V$		-24	mA
	Low lovel output ourrent	$V_{CC} = 2.7 V$		12	mA
I _{OL}	Low-level output current	V _{CC} = 3 V			IIIA
T_A	Operating free-air temperature		-40	125	°C

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V _{cc}	MIN	TYP ⁽¹⁾	MAX	UNIT
	$I_{OH} = -100 \mu A$	2.7 V to 3.6 V	V _{CC} - 0.2				
V/	12 mA		2.7 V	2.2			V
V _{OH}	I _{OH} = -12 IIIA	$I_{OH} = -12 \text{ mA}$					
	$I_{OH} = -24 \text{ mA}$		3 V	2.2			
	I _{OL} = 100 μA		2.7 V to 3.6 V			0.2	
V _{OL}	I _{OL} = 12 mA	2.7 V			0.4	V	
	I _{OL} = 24 mA	3 V	3 V 0.55				
I _I	$V_1 = 0 \text{ to } 5.5 \text{ V}$		3.6 V			±5	μΑ
I _{OZ}	V _O = 0 to 5.5 V		3.6 V			±15	μΑ
	$V_I = V_{CC}$ or GND	I _O = 0	3.6 V			10	^
I _{CC}	$3.6 \text{ V} \le \text{V}_1 \le 5.5 \text{ V}^{(2)}$	3.6 V			10	μΑ	
Δl _{CC}	One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or G	SND	2.7 V to 3.6 V			500	μΑ
C _i	$V_I = V_{CC}$ or GND		3.3 V		4		pF
C _o	$V_O = V_{CC}$ or GND		3.3 V		5.5		pF

All typical values are at V_{CC} = 3.3 V, T_{A} = $25^{\circ}C.$ This applies in the disabled state only.

SN74LVC540A-EP OCTAL BUFFER/DRIVER WITH 3-STATE OUTPUTS





Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 2	2.7 V	V _{CC} = 3 ± 0.3	UNIT	
	(INFOT)	(OOTPOT)	MIN	MAX	MIN	MAX	
t _{pd}	Α	Y		7.1	1	5.3	ns
t _{en}	ŌĒ	Y		8	1	6.6	ns
t _{dis}	ŌE	Y		8.2	1	7.4	ns

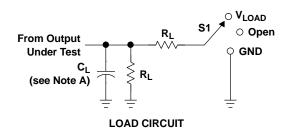
Operating Characteristics

 $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	UNIT		
0	Dower discipation conscitance nor buffer/driver	Outputs enabled	f = 10 MHz	56	31	pF	
C _{pd}	Power dissipation capacitance per buffer/driver	Outputs disabled	I = IU IVIMZ	3	3	рг	

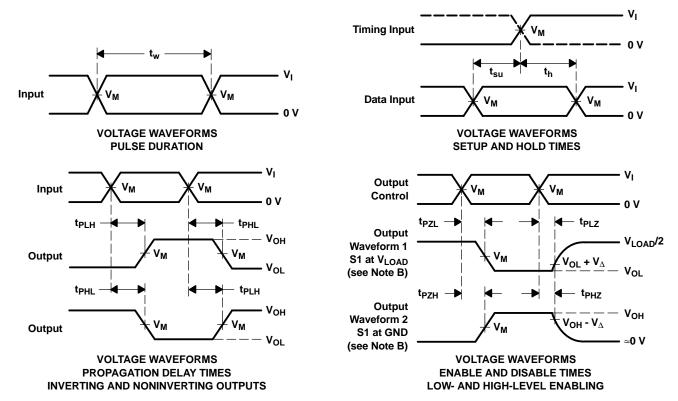


PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

.,	INPUTS		.,	.,	•	_	.,	
V _{CC}	V _{CC} V _I 1	t _r /t _f	V _M	V _{LOAD}	CL	RL	V_Δ	
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V	
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V	



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω .
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGE OPTION ADDENDUM



10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
SN74LVC540AQDWREP	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C540AEP	Samples
SN74LVC540AQPWREP	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C540AEP	Samples
V62/04665-01XE	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C540AEP	Samples
V62/04665-01YE	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C540AEP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

10-Dec-2020

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OTHER QUALIFIED VERSIONS OF SN74LVC540A-EP:

■ Catalog: SN74LVC540A

Automotive: SN74LVC540A-Q1

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC540AQDWREP	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LVC540AQPWREP	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC540AQDWREP	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LVC540AQPWREP	TSSOP	PW	20	2000	356.0	356.0	35.0

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